Call for Letters in the IEEE Transaction of Power Electronics (TPEL)

Special Section on Patent Related Short Articles

Scheduled Publication Time: May 2023

This first ever TPEL Letters special section on “Patent Related Short Articles” focuses on the collection of short articles describing new ideas and concepts that has been patented in recent years. The topics across all areas of TPEL are eligible. The Letters from this special section aims at improving the visibility of recently patented ideas to a wide range of audience. It can also highlight the new development since the patent filing, idea adoption in practice, as well as impact of power electronics development on the industry and society. This special section can enable the exchange of knowledge and facilitate further research on new concepts for power electronics technologies.

To submit a Letter to this special Section, please select type “Letter” in the TPEL Manuscript Central, and Special Section on “Patent Related Short Articles”.

Requirements: It is required the Letters in this special section list the granted patent as a reference (open access and in English), with only brief review of the patented idea. The Letter should instead focus on further development and application of the idea, with minimum overlap with the content in the patent. It is recommended the published patent is uploaded as supplementary file during the manuscript submission process. This also applies if the authors are not the inventors of the patents, where the submitted Letters should focus on the authors’ own original ideas and development (technical improvements, alternatives, etc.).

TPEL Letters focus on new ideas and fundamental concepts in the area of power electronics. TPEL Letters is now a part of the Transactions on Power Electronics, published together with regular papers with the same impact factor, but has shorter review cycles with the emphasis on rapid publications. The typical review cycle for a Letter submission is 6 to 8 weeks.

Letters are limited to 4 pages for the first submission. Submissions longer than this limit will be returned without review. Revisions may be slightly longer to address the review comments. Accepted Letters longer than 4 pages are subject to over page charge. All submissions should be in a double-column format. For more information concerning TPEL letter submission, please refer to: https://www.ieee-pels.org/publications/tpel-letters

Deadline for Submission of Manuscript: December 1, 2022 (UPDATE: Extended to December 15, 2022)

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Proposed timeline

- August 1, 2022 – Call for Letters Announcement
- December 1, 2022 – Manuscripts Submission Deadline
- January 15, 2023 – Final Decision Notification
- February 1, 2023 – Manuscripts Forwarded to IEEE for Publication
- February 15, 2023 – Manuscripts Published Online as Early Access
- May 1, 2023 – Special Section Published in an IEEE TPEL Issue